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(12) **United States Design Patent** (10) **Patent No.:** **US D771,168 S**
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(54) **WIRE BONDING CERAMIC CAPILLARY**

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(**) Term: **14 Years**

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(52) **U.S. Cl.**
USPC **D15/144**

(58) **Field of Classification Search**
USPC D15/144, 144.2, 199; D8/30; D19/66,
D19/200; 228/4.5, 1.1, 180.5
CPC . B23K 20/004; B23K 20/005; B23K 20/106
See application file for complete search history.

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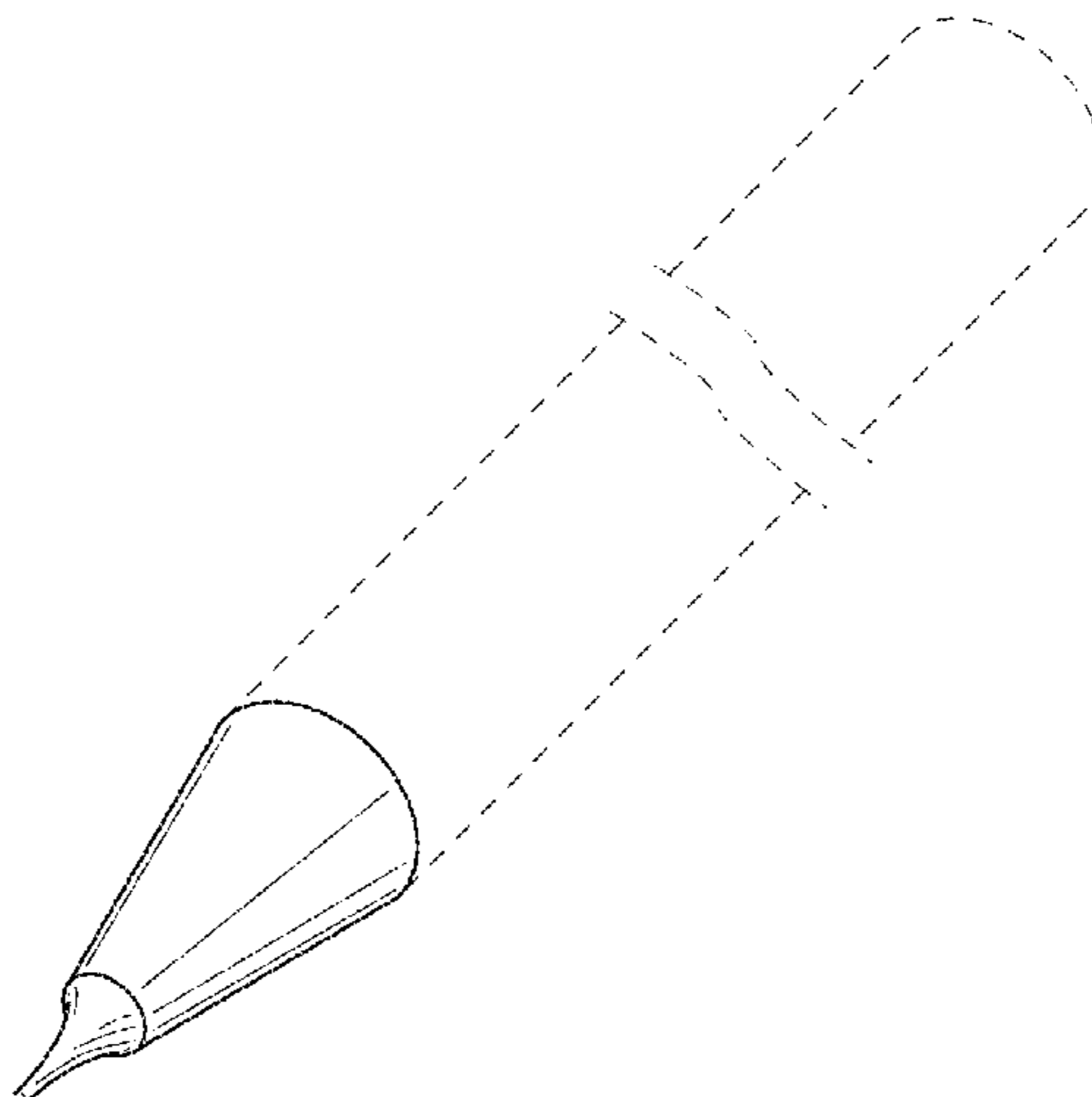
(57) **CLAIM**

The ornamental design for a wire bonding ceramic capillary, as shown and described.

DESCRIPTION

FIG. 1 depicts a first perspective view of a wire bonding ceramic capillary.
FIG. 2 depicts a second perspective view thereof;
FIG. 3 depicts a top plan view thereof;
FIG. 4 depicts a side elevation view thereof; and,
FIG. 5 depicts a bottom plan view thereof.
The broken lines in the drawings illustrate environmental structure on the article and form no part of the claimed design.

1 Claim, 2 Drawing Sheets



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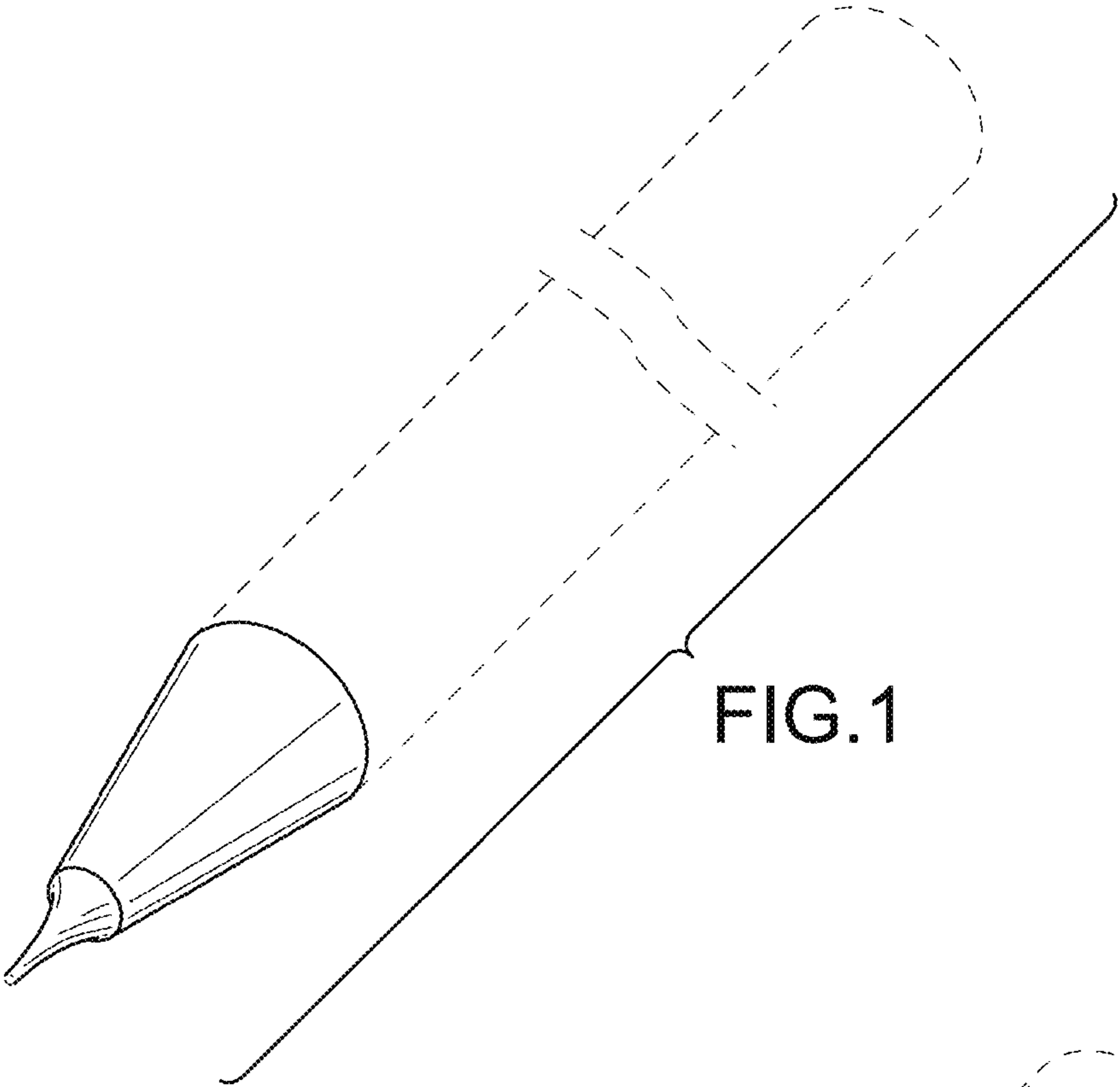


FIG.1

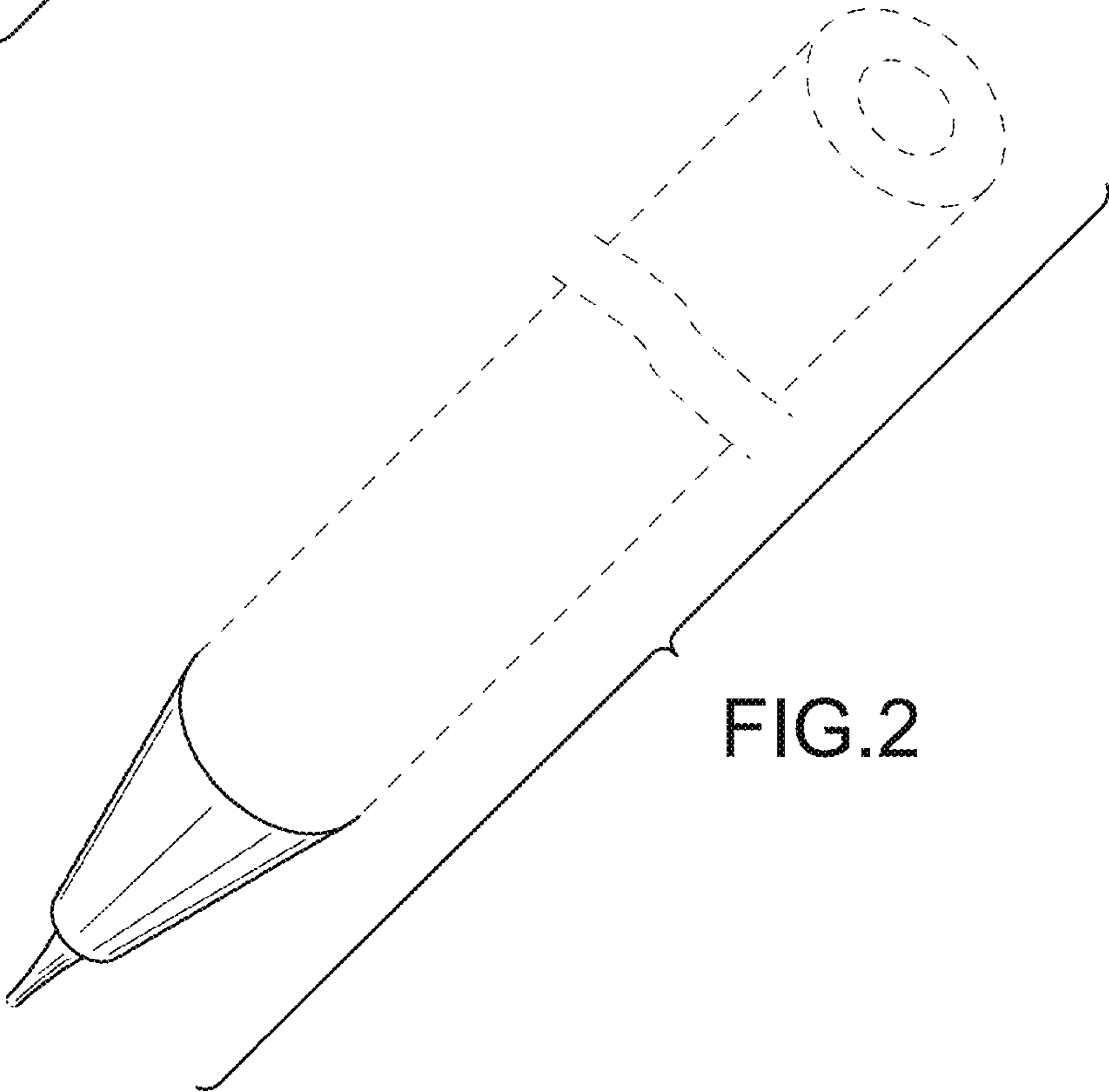


FIG.2

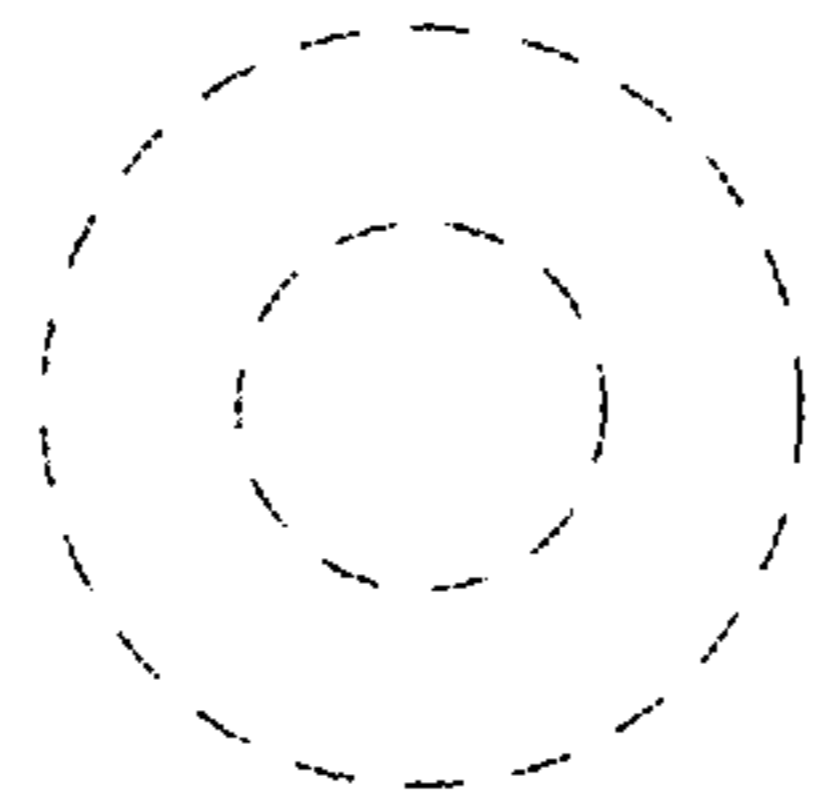


FIG. 3

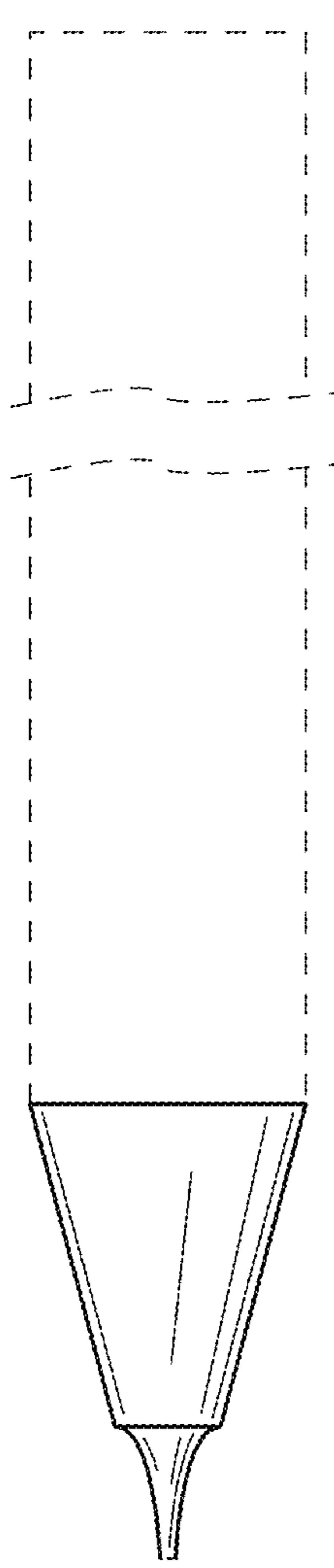


FIG. 4

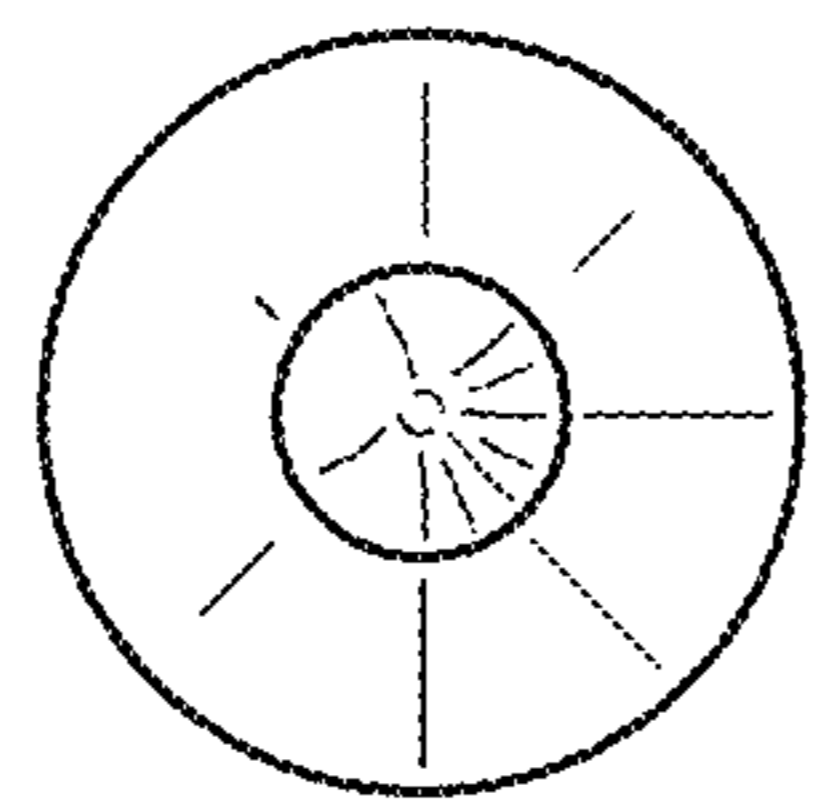


FIG. 5